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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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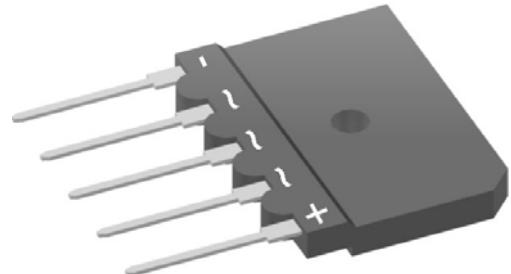
Standard Rectifier

3~ Rectifier
$V_{RRM} = 1600 \text{ V}$
$I_{DAV} = 40 \text{ A}$
$I_{FSM} = 370 \text{ A}$

3~ Rectifier Bridge

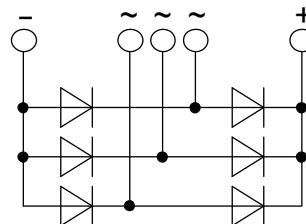
Part number

GUO40-16NO1



Backside: isolated

E72873



Features / Advantages:

- Low forward voltage drop
- Planar passivated chips
- Easy to mount with one screw
- Space and weight savings

Applications:

- Supplies for DC power equipment
- Input rectifiers for PWM inverter
- Battery DC power supplies
- Field supply for DC motors

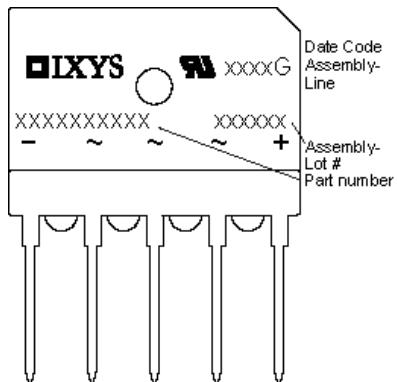
Package: GUFP

- Isolation Voltage: 2500 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Base plate: Plastic overmolded tab
- Reduced weight

Rectifier

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1700	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			1600	V
I_R	reverse current	$V_R = 1600 V$ $V_R = 1600 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		40 1.5	μA mA
V_F	forward voltage drop	$I_F = 10 A$ $I_F = 30 A$ $I_F = 10 A$ $I_F = 30 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		1.06 1.28 0.92 1.23	V V
I_{DAV}	bridge output current	$T_C = 90^\circ C$ rectangular $d = \frac{1}{3}$	$T_{VJ} = 175^\circ C$		40	A
V_{FO} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 175^\circ C$		0.74 16.3	V $m\Omega$
R_{thJC}	thermal resistance junction to case				4.3	K/W
R_{thCH}	thermal resistance case to heatsink			0.50		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		35	W
I_{FSM}	max. forward surge current	$t = 10 ms; (50 Hz)$, sine $t = 8,3 ms; (60 Hz)$, sine	$T_{VJ} = 45^\circ C$ $V_R = 0 V$		370 400	A
		$t = 10 ms; (50 Hz)$, sine $t = 8,3 ms; (60 Hz)$, sine	$T_{VJ} = 150^\circ C$ $V_R = 0 V$		315 340	A
I^2t	value for fusing	$t = 10 ms; (50 Hz)$, sine $t = 8,3 ms; (60 Hz)$, sine	$T_{VJ} = 45^\circ C$ $V_R = 0 V$		685 665	A^2s
		$t = 10 ms; (50 Hz)$, sine $t = 8,3 ms; (60 Hz)$, sine	$T_{VJ} = 150^\circ C$ $V_R = 0 V$		495 480	A^2s
C_J	junction capacitance	$V_R = 400 V; f = 1 MHz$	$T_{VJ} = 25^\circ C$	10		pF

Package GUFP			Ratings		
Symbol	Definition	Conditions	min.	typ.	max.
I_{RMS}	$RMS\ current$	per terminal			70
T_{VJ}	<i>virtual junction temperature</i>		-40		175
T_{op}	<i>operation temperature</i>		-40		150
T_{stg}	<i>storage temperature</i>		-40		150
Weight				8.5	g
M_D	<i>mounting torque</i>		0.8		1.2
F_c	<i>mounting force with clip</i>		20		120
$d_{Spp/App}$	<i>creepage distance on surface / striking distance through air</i>		terminal to terminal	6.7	5.4
$d_{Spb/Abp}$			terminal to backside	10.0	8.0
V_{ISOL}	<i>isolation voltage</i>	$t = 1\ second$ $t = 1\ minute$ 50/60 Hz, RMS; $I_{ISOL} \leq 1\ mA$	2500 2080		V V
R_{thJA}	<i>thermal resistance junction to ambient</i>			50	K/W

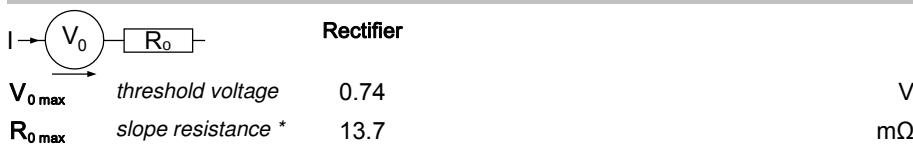


Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	GUO40-16NO1	GUO40-16NO1	Tube	14	514899

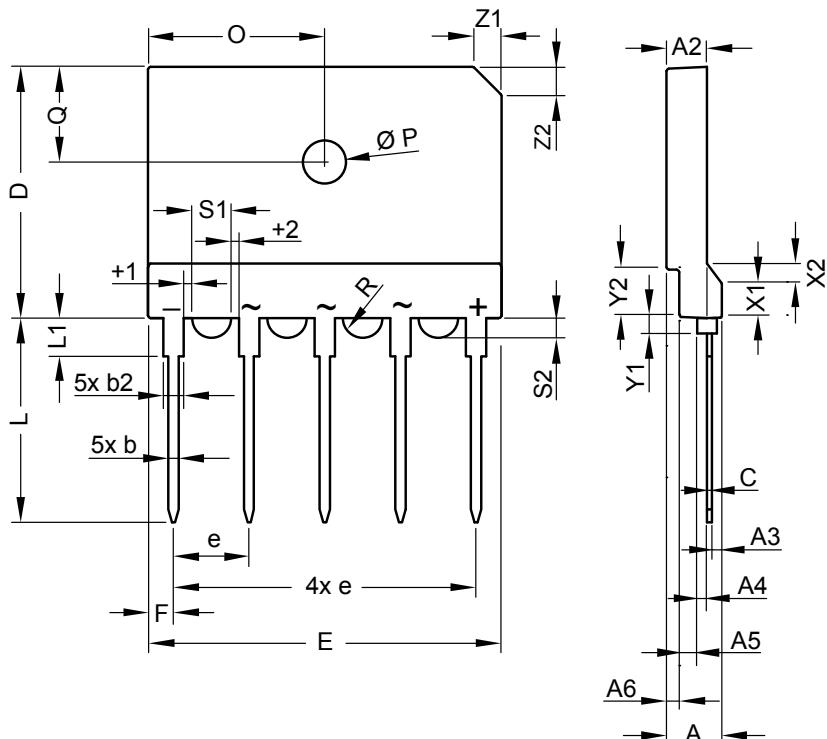
Similar Part	Package	Voltage class
DNA40U2200GU	GUFP	2200
DMA40U1800GU	GUFP	1800
GUO40-12NO1	GUFP	1200
GUO40-08NO1	GUFP	800

Equivalent Circuits for Simulation

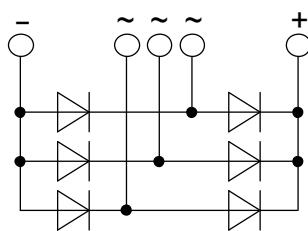
* on die level

 $T_{VJ} = 175\ ^\circ C$ 

Outlines GUFP



Dim.	Millimeter			Inches		
	min	typ.	max	min	typ.	max
A	5.40	5.50	5.60	0.213	0.217	0.221
A2	3.90	4.00	4.10	0.154	0.158	0.162
A3	0.95	1.00	1.10	0.037	0.039	0.043
A4	0.95	1.00	1.05	0.037	0.039	0.041
A5	1.60	1.70	1.80	0.063	0.067	0.071
A6	1.25	1.30	1.35	0.049	0.051	0.053
b	0.95	1.00	1.05	0.037	0.039	0.041
b2	1.95	2.00	2.05	0.077	0.079	0.081
C	0.45	0.50	0.55	0.018	0.020	0.022
D	24.80	25.00	25.20	0.977	0.985	0.993
E	34.70	35.00	35.30	1.367	1.379	1.391
e	BSC 7.50			BSC 0.296		
F	2.40	2.50	2.60	0.095	0.099	0.102
L	20.30	20.40	20.50	0.800	0.804	0.808
L1	3.70	3.75	3.80	0.146	0.148	0.150
O	17.40	17.50	17.60	0.686	0.690	0.693
ØP	4.10	4.20	4.30	0.162	0.165	0.169
Q	9.20	9.30	9.40	0.362	0.366	0.370
Ø _{1/2} R	1.77			0.070		
s1	3.45	3.50	3.55	0.136	0.138	0.140
s2	1.45	1.50	1.55	0.057	0.059	0.061
t1	0.95	1.00	1.05	0.037	0.039	0.041
t2	0.95	1.00	1.05	0.037	0.039	0.041
x1	3.20	3.30	3.40	0.126	0.130	0.134
x2	1.90	2.00	2.10	0.075	0.079	0.083
y1	1.60	1.65	1.70	0.063	0.065	0.067
y2	4.65	4.70	4.75	0.183	0.185	0.187
z1	2.80	2.90	3.00	0.110	0.114	0.118



Rectifier

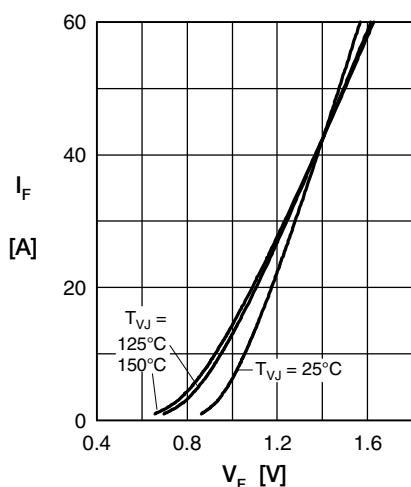


Fig. 1 Forward current vs. voltage drop per diode

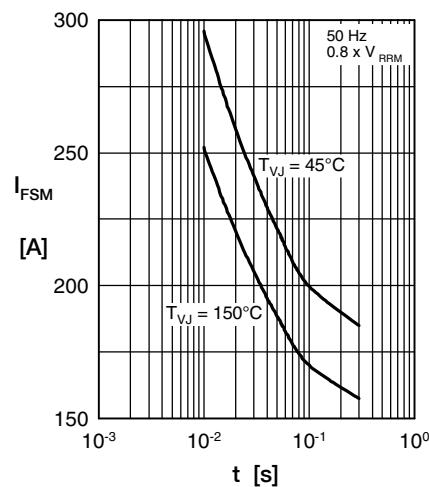


Fig. 2 Surge overload current vs. time per diode

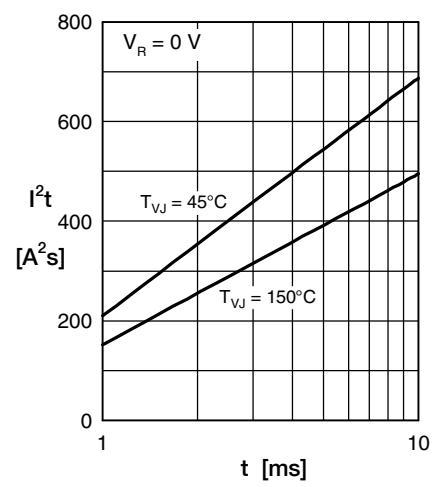
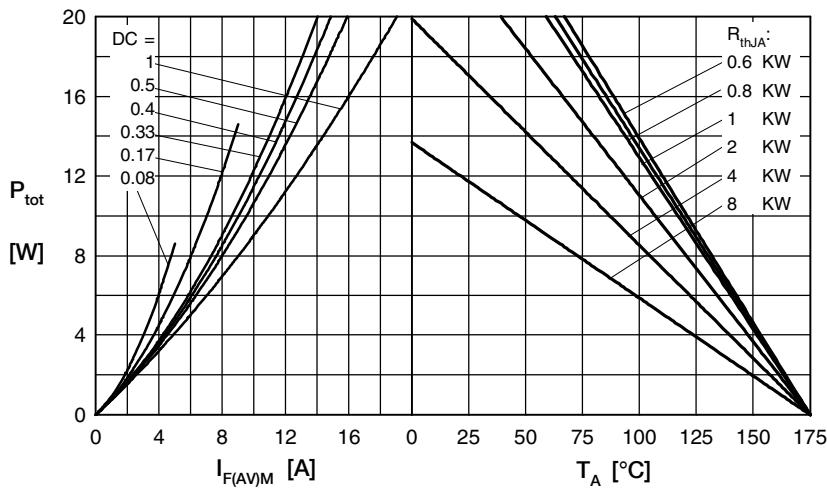
Fig. 3 I^2t vs. time per diode

Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

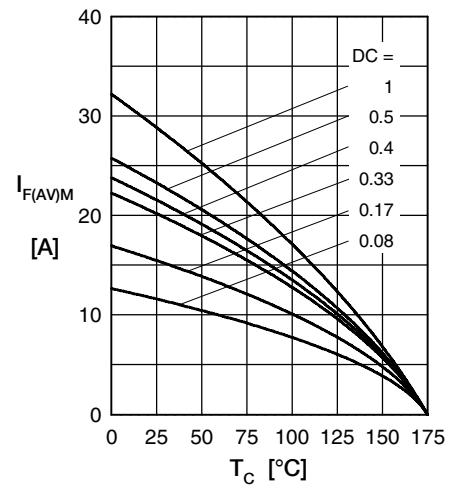


Fig. 5 Max. forward current vs. case temperature per diode

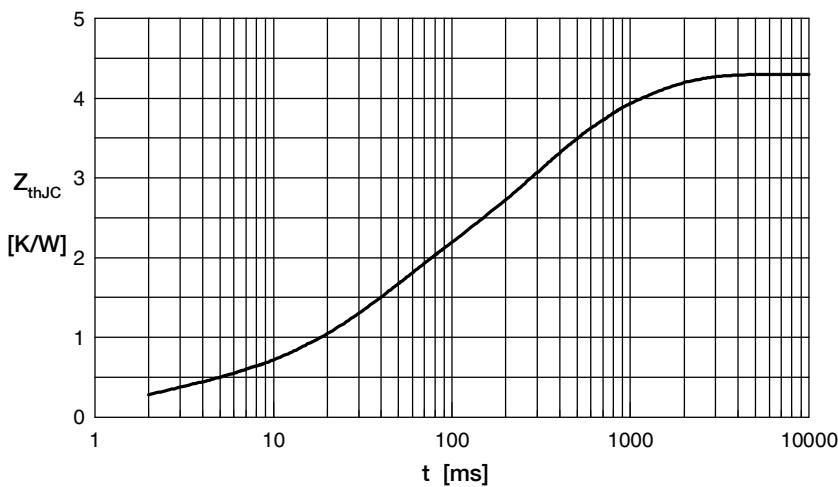


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for Z_{thJC} calculation:

i	R_{th} (K/W)	t_i (s)
1	0.302	0.002
2	1.252	0.032
3	1.582	0.227
4	1.164	0.820